

SANDIA TALKS

HOW TO “PHOTOCOPY” A PRINTED CIRCUIT BOARD

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WHAT'S THE PROBLEM?



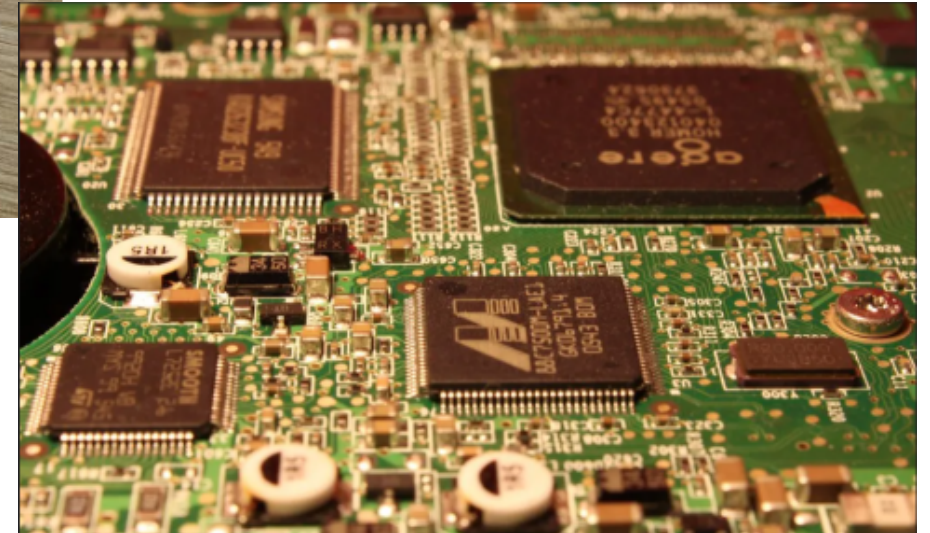
HOW AND WHY TO COPY



2D printing



3D printing functional devices

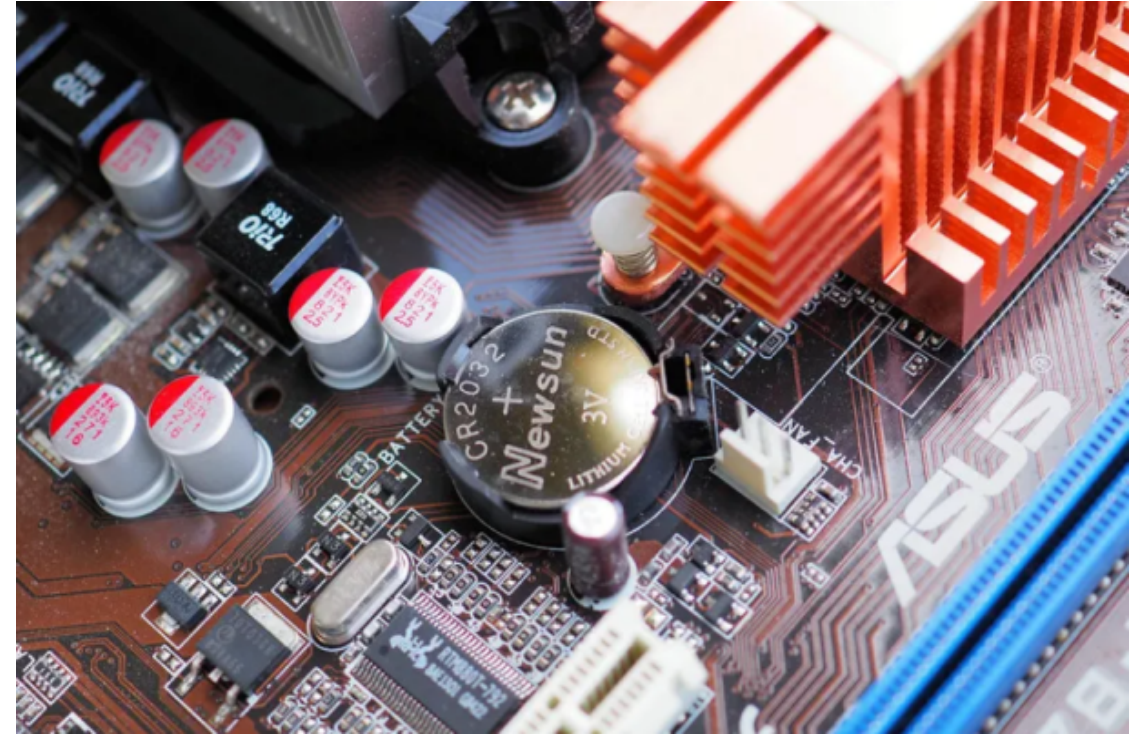


Circuit board?

XRAY/CT



Bag of water with some bones

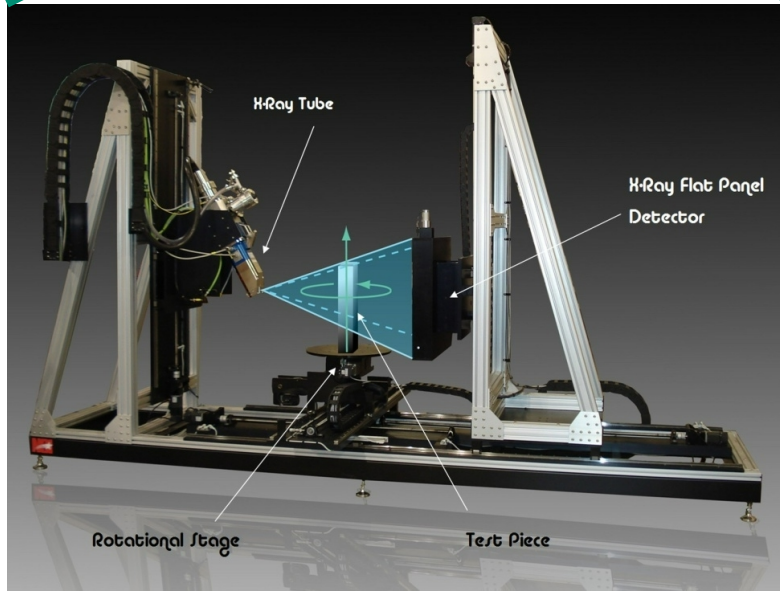


Lots of metal
Multiple heterogeneous materials
Multiple important layers
Very small features (50 microns)

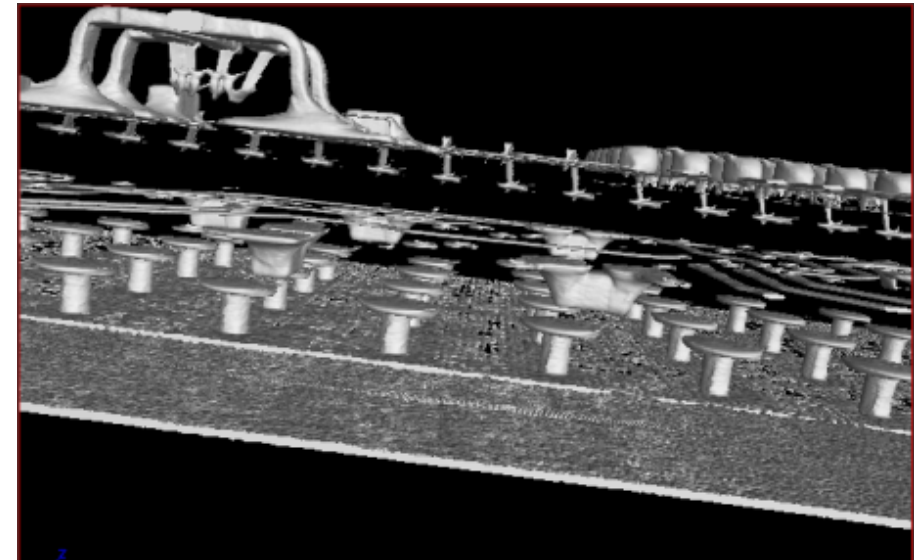
INDUSTRIAL XRAY SYSTEM



2D Xray

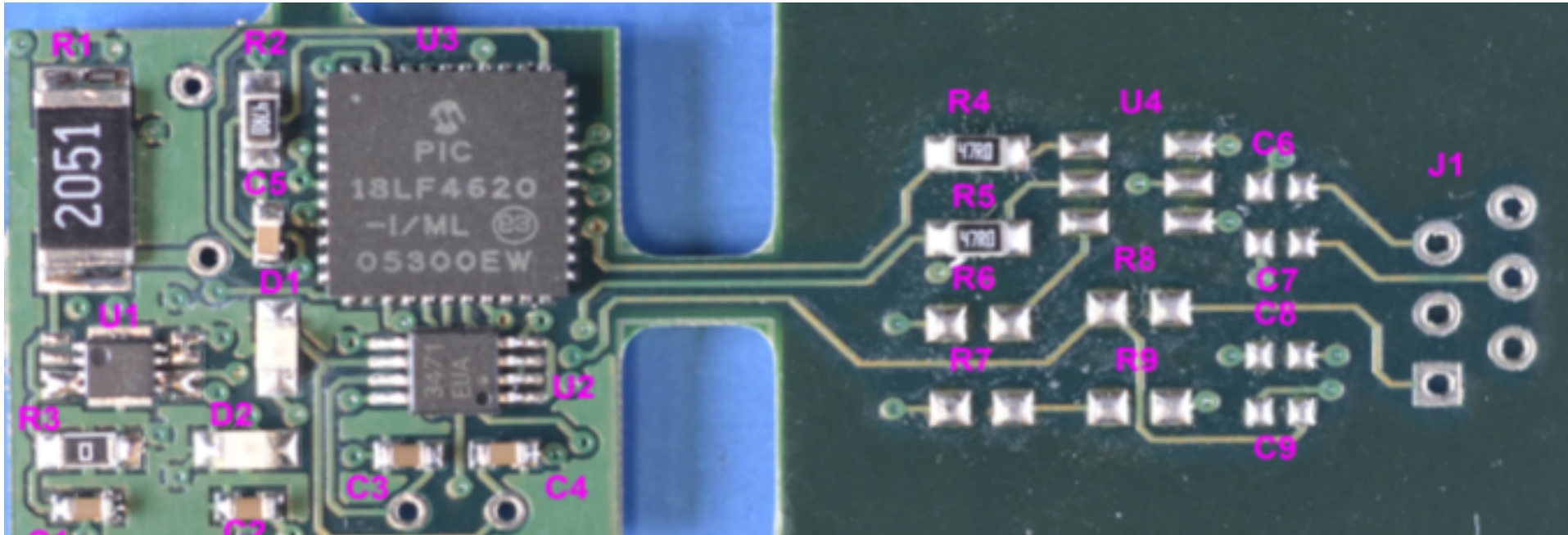


3D CT



CAPABILITY PROCESS

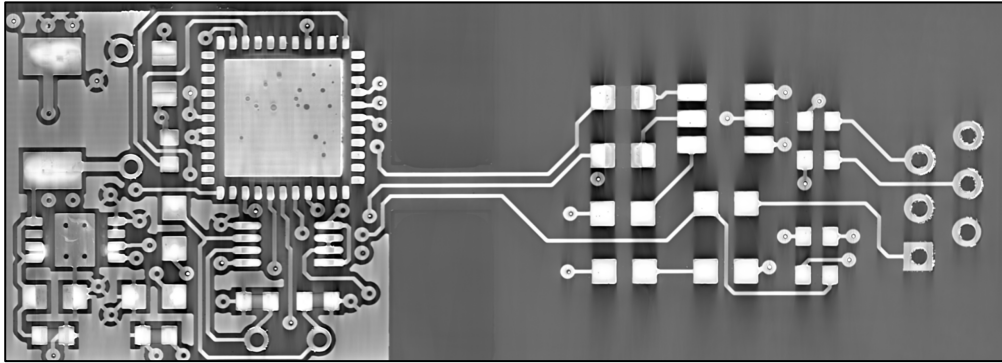
Original



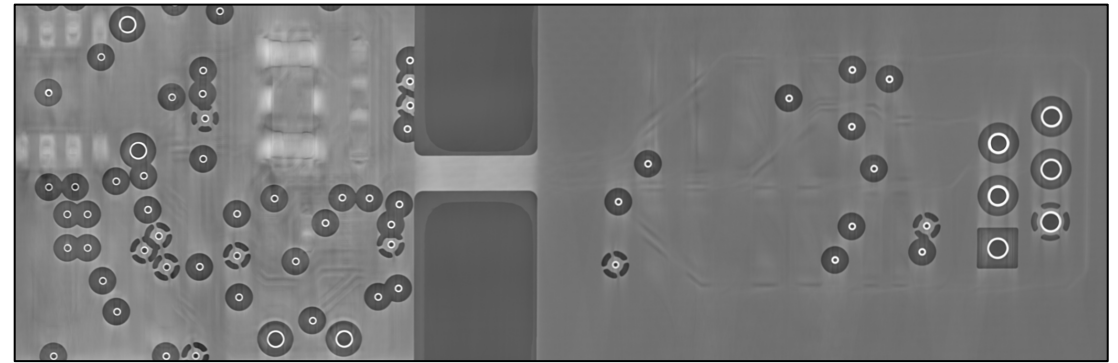
CAPABILITY PROCESS

X-ray

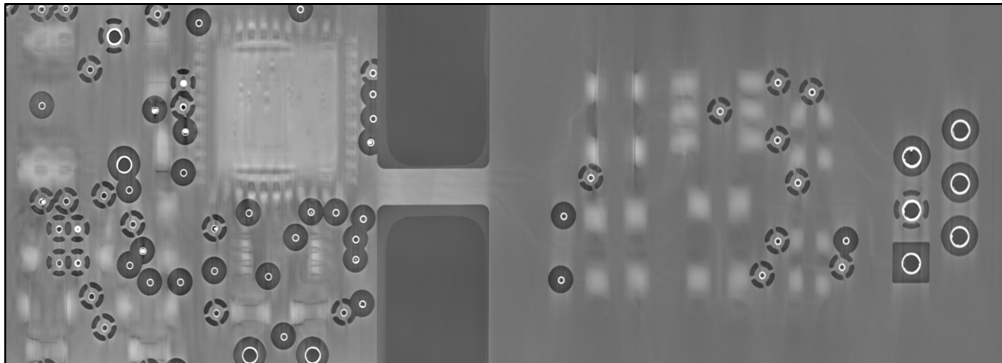
Layer 1



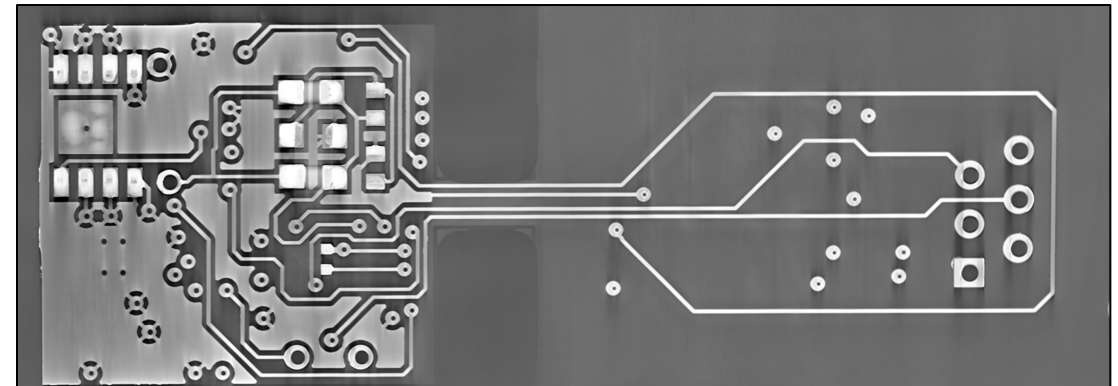
Layer 2



Layer 3

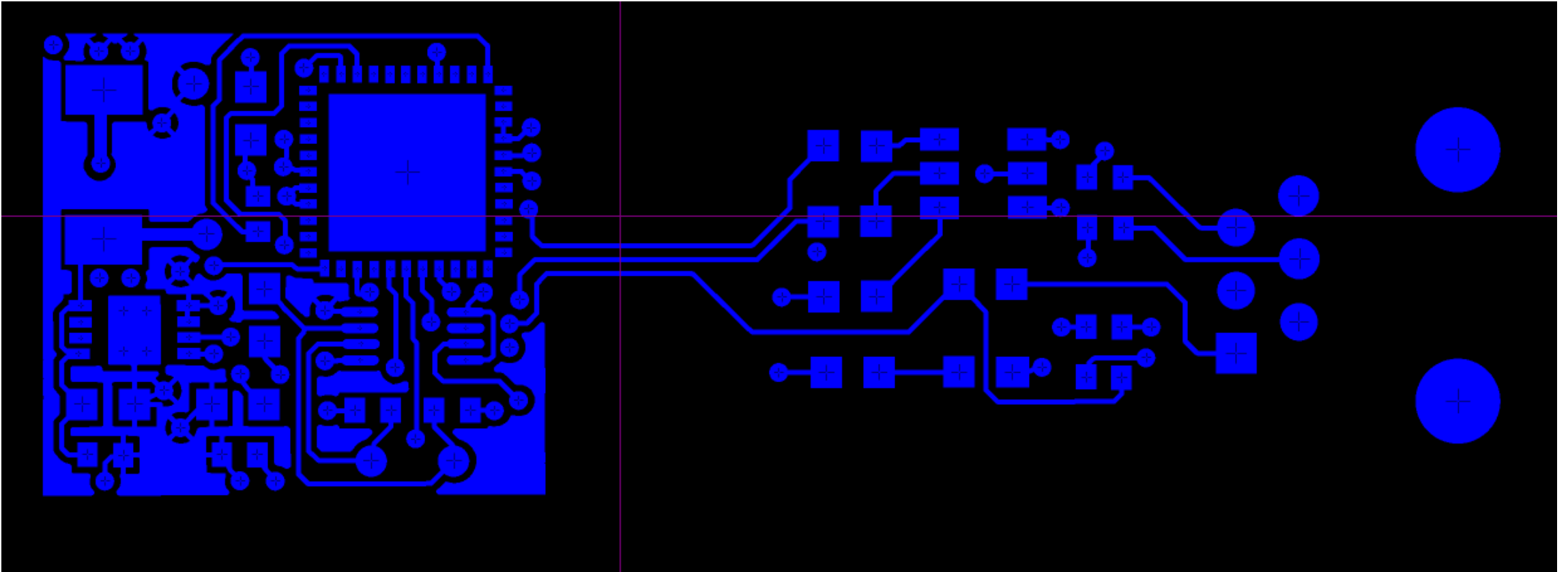


Layer 4



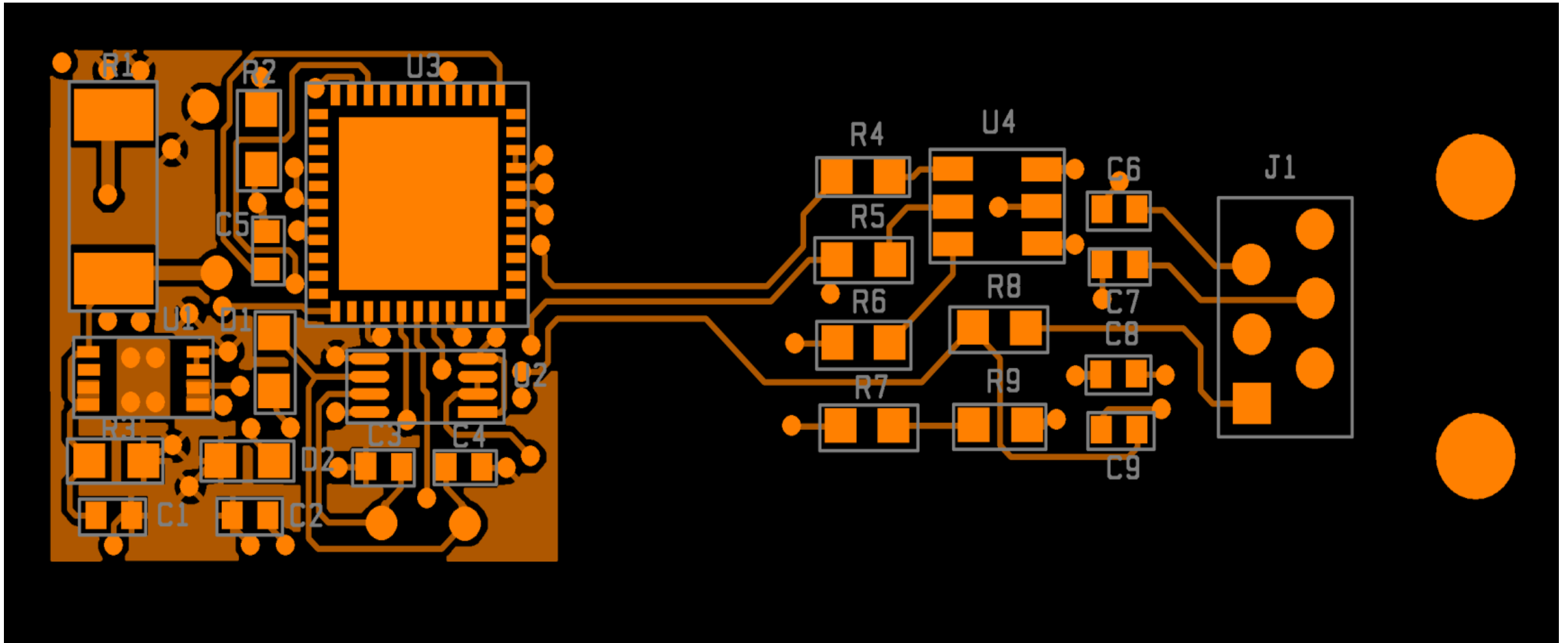
CAPABILITY PROCESS

Binary



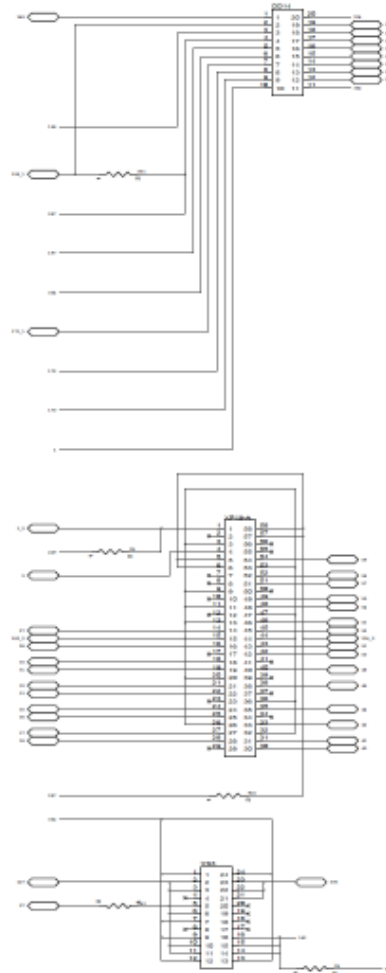
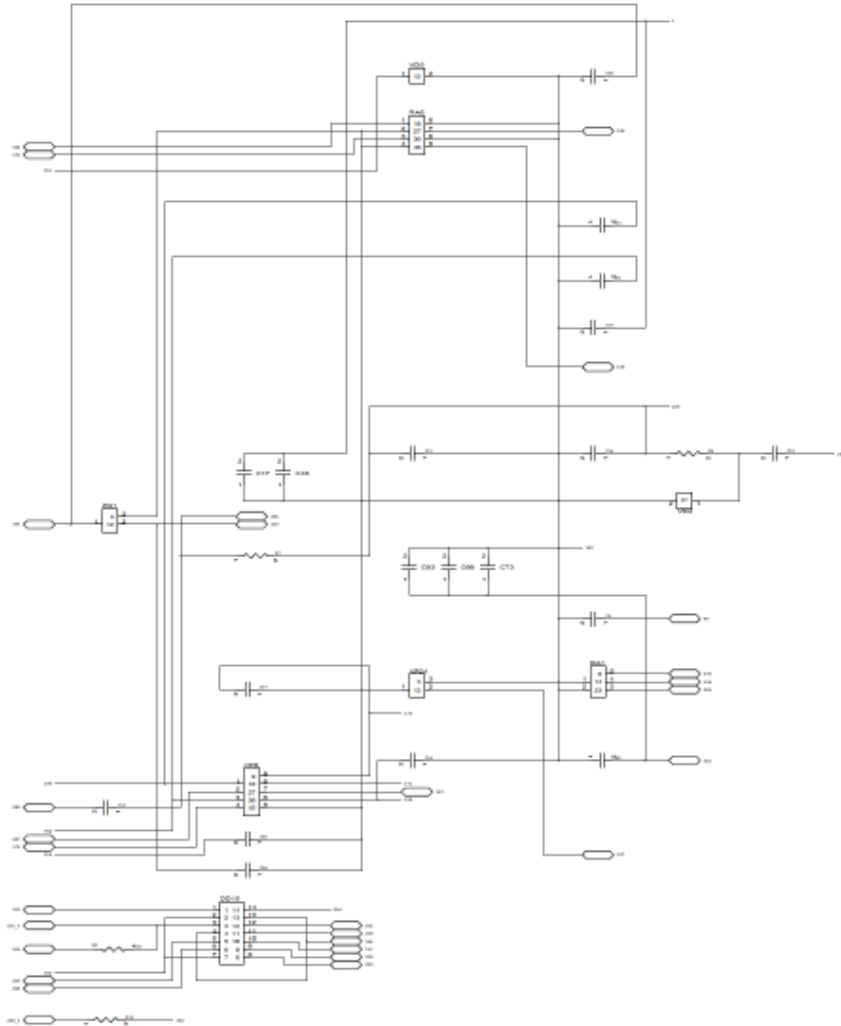
CAPABILITY PROCESS

Design Files

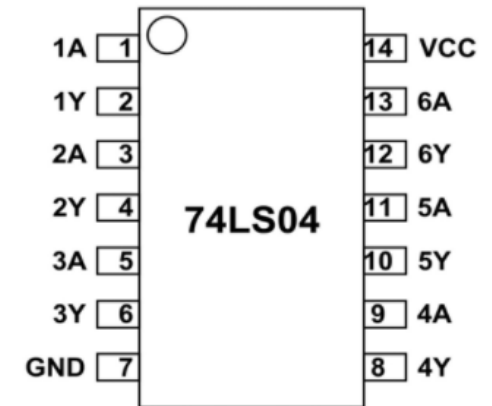


CAPABILITY PROCESS

Schematic

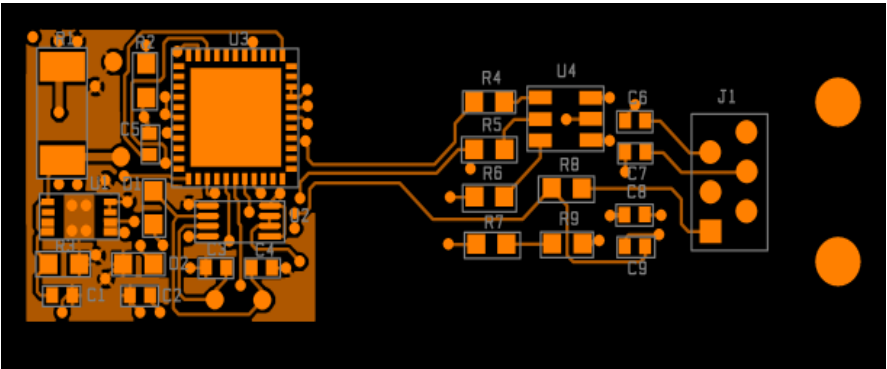


Bill of Materials

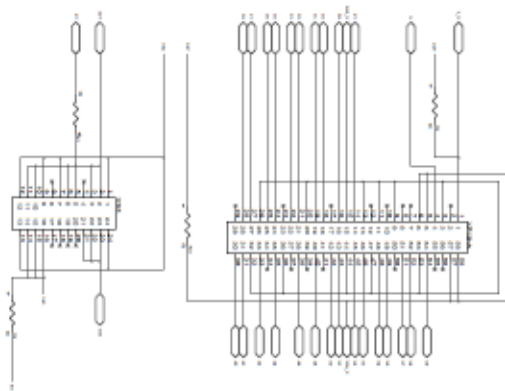


CAPABILITY PROCESS

Design Files



Schematic

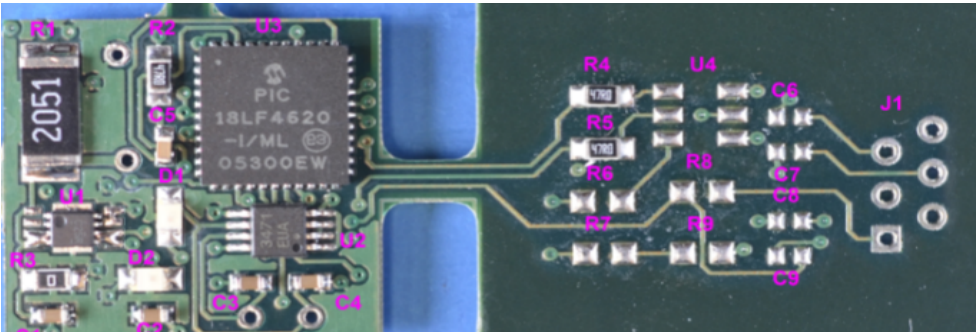


Bill of Materials



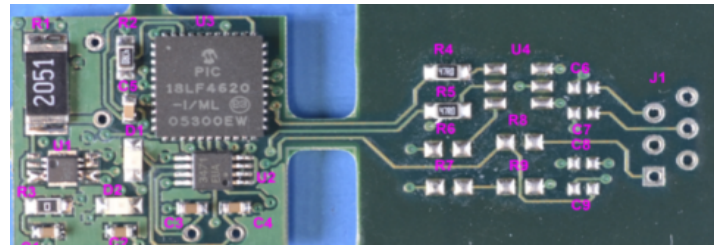
1A	1	14	VCC
1Y	2	13	6A
2A	3	12	6Y
2Y	4	11	5A
3A	5	10	5Y
3Y	6	9	4A
GND	7	8	4Y

Copy

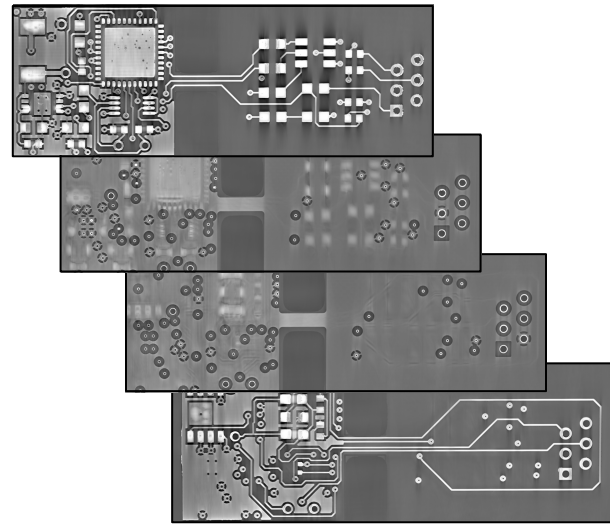


CAPABILITY PROCESS

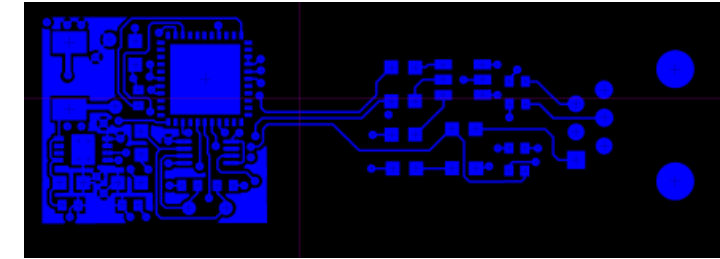
Original



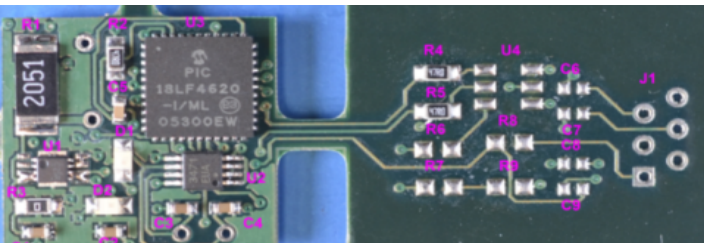
X-ray



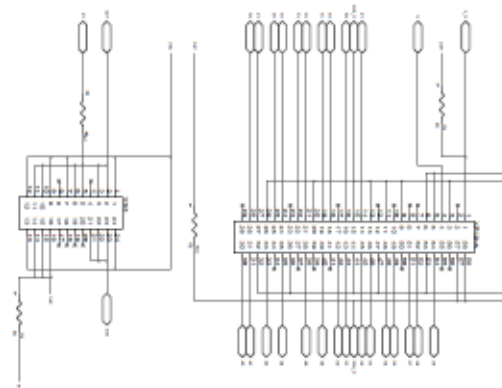
Binary



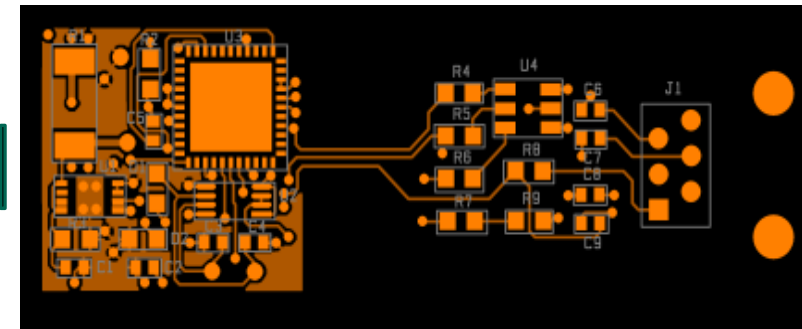
Copy



Schematic/Bill of Materials



Design Files



SANDIA TALKS

THANK
YOU

